

Part Number: **BZT52Cxx-p-F (Date Code 0832+)**  
Weight (mg): 5.2423

p = package designator  
See Data Sheet

xx= 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 2V0,  
2V4, 2V, 30, 33, 36, 39, 3V0, 3V3, 3V6, 3V9,  
43, 47, 4V3, 4V7, 51, 5V1, 5V6, 6V2, 6V8, 7V5,  
8V2, 9V1

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.44	0.1509	1000000	28785
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	3.41	2.0809	576500	228838
		Ni	7440-02-0	41.00%			410000	162747
		Mn	7439-96-5	0.60%			6000	2382
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	397
		Co	7440-48-4	0.50%			5000	1985
		Si	7440-21-3	0.15%			1500	595
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.40	0.0606	1000000	11560
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.10	0.0512	1000000	9767
Encapsulation	CEL-1620HF-9	Silica	60676-86-0	77.00%	5.52	2.8268	770000	415206
		Basic Duromer: Epoxy resin (Compound of a polymeric network)	----	11.00%			110000	59315
		Basic Duromer: Phenolic resin (Compound of polymeric network)	----	6.60%			66000	35589
		Misc. system	system	5.00%			50000	26961
		Carbon black	1333-86-4	0.40%			4000	2157
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.33	0.0719	1000000	13715
					Total	10.19	5.2423	1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

\* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including <b>DecaBDE</b>
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)